MÜNCHEN

Plan of the fair grounds



EMS Electronic manufacturing services, A1/B1 PCBs and other circuit carriers Electromechanics and system peripherals. Interconnection components Electromechanics and system peripherals, Interconnection components, Relays, switches and keyboards Electromechanics and system peripherals, Interconnection components, Casing technology EMS Electronics manufacturing services, PCBs and other circuit carriers, Electromechanics and system peripherals, Semiconductors Test and measurement Power supplies A5-6 Passive components Sensor technology, Micro- and nanosystems (NEMS, MEMS) all halls Embedded systems Semiconductors Displays all halls Automotive В6 Wireless SEMICON Europa 2024 ED/EDA / Servo-technology / Assemblies and subsystems / Services all halls ICM

Conferences

electronica

Automotive Conference Wireless Congress

SEMICON Europa Conferences

- Fab Management Forum (FMF)
- Advanced Packaging Conference (APC)

SEMI Conferences

MEMS & Imaging Sensors Summit

Supporting program:





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